Preferred Device

# **Sensitive Gate Triacs**

# Silicon Bidirectional Thyristors

Designed for industrial and consumer applications for full wave control of ac loads such as appliance controls, heater controls, motor controls, and other power switching applications.

- Sensitive Gate Allows Triggering by Microcontrollers and other Logic Circuits
- Uniform Gate Trigger Currents in Three Quadrants; Q1, Q2, and Q3
- High Immunity to dv/dt 25 V/μs Minimum at 110°C
- High Commutating di/dt 8.0 A/ms Minimum at 110°C
- Maximum Values of IGT, VGT and IH Specified for Ease of Design
- On-State Current Rating of 8 Amperes RMS at 70°C
- High Surge Current Capability 70 Amperes
- Blocking Voltage to 800 Volts
- Rugged, Economical TO220AB Package
- Device Marking: Logo, Device Type, e.g., MAC8SM, Date Code

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1)  (T <sub>J</sub> = -40 to 110°C, Sine Wave, 50 to 60 Hz, Gate Open)  MAC8SD  MAC8SM  MAC8SN	V <sub>DRM</sub> , V <sub>RRM</sub>	400 600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T <sub>C</sub> = 70°C)	I <sub>T(RMS)</sub>	8.0	Α
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, T <sub>J</sub> = 110°C)	I <sub>TSM</sub>	70	A
Circuit Fusing Consideration (t = 8.3 ms)	l <sup>2</sup> t	20	A <sup>2</sup> sec
Peak Gate Power (Pulse Width $\leq$ 1.0 $\mu$ s, T <sub>C</sub> = 70°C)	$P_{GM}$	16	V
Average Gate Power (t = 8.3 ms, T <sub>C</sub> = 70°C)	P <sub>G(AV)</sub>	0.35	V
Operating Junction Temperature Range	TJ	- 40 to +110	ç
Storage Temperature Range	T <sub>stg</sub>	- 40 to +150	°C

<sup>1.</sup>  $V_{DRM}$  and  $V_{RRM}$  for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

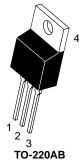


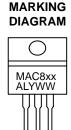
#### ON Semiconductor®

http://onsemi.com

# **TRIACS 8 AMPERES RMS** 400 thru 800 VOLTS







**CASE 221A** Style 4

= Specific Device Code = Assembly Location

= Wafer Lot = Year WW = Work Week

PIN ASSIGNMENT			
1	Main Terminal 1		
2	Main Terminal 2		
3	Gate		
4	Main Terminal 2		

#### ORDERING INFORMATION

Device	Package	Shipping
MAC8SD	TO220AB	50 Units/Rail
MAC8SM	TO220AB	50 Units/Rail
MAC8SN	TO220AB	50 Units/Rail

Preferred devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance - Junction to Case - Junction to Ambient	$R_{ heta JC} \ R_{ heta JA}$	2.2 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

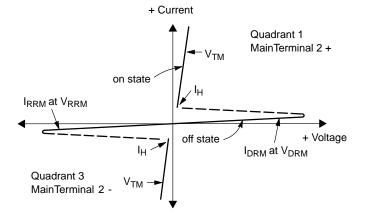
#### **ELECTRICAL CHARACTERISTICS** (T<sub>1</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	,			-	+
Peak Repetitive Blocking Current $(V_D = Rated \ V_{DRM}, \ V_{RRM}; \ Gate \ Open) \\ T_J = 25^{\circ} \\ T_J = 110^{\circ}$			-	0.01 2.0	mA
ON CHARACTERISTICS	<u>.</u>				•
Peak On-State Voltage* (I <sub>TM</sub> = ±11A)	V <sub>TM</sub>	-	-	1.85	V
Gate Trigger Current (Continuous dc) ( $V_D$ = 12 V, $R_L$ = 100 $\Omega$ ) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)	I <sub>GT</sub>	- - -	2.0 3.0 3.0	5.0 5.0 5.0	mA
Holding Current ( $V_D$ = 12V, Gate Open, Initiating Current = $\pm$ 150m/	A) I <sub>H</sub>	-	3.0	10	mA
Latching Current ( $V_D$ = 24V, $I_G$ = 5mA) MT2(+), G(+) MT2(-), G(-) MT2(+), G(-)	IL	- - -	5.0 10 5.0	15 20 15	mA
Gate Trigger Voltage (Continuous dc) ( $V_D$ = 12 V, $R_L$ = 100 $\Omega$ ) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)	V <sub>GT</sub>	0.45 0.45 0.45	0.62 0.60 0.65	1.5 1.5 1.5	Volts
DYNAMIC CHARACTERISTICS					
Rate of Change of Commutating Current $V_D=400~V,~I_{TM}=3.5~A,~Commutating~dv/dt=10~V~\mu/sec,~Gate~Open,~T_J=110^{\circ}C,~f=500~Hz,~Snubber:~C_S=0.01~\mu F,~R_S=15~\Omega,~See~Figure~16.)$	di/dt <sub>(c)</sub>	8.0	10	-	A/ms
Critical Rate of Rise of Off-State Voltage ( $V_D$ = Rate $V_{DRM}$ , Exponential Waveform, $R_{GK}$ = 510 $\Omega$ , $T_J$ = 110	dv/dt	25	75	-	V/µs

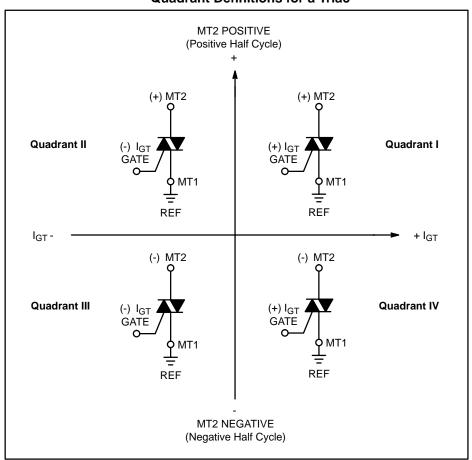
<sup>\*</sup>Indicates Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle ≤ 2%.

# Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
IH	Holding Current

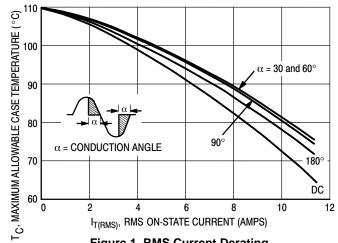


#### **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.



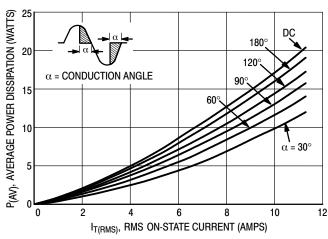
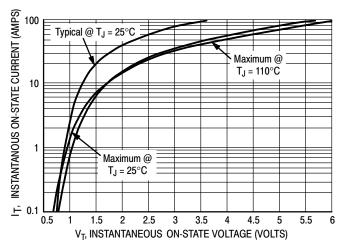


Figure 1. RMS Current Derating

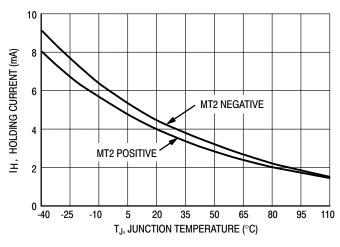
Figure 2. Maximum On-State Power Dissipation



R(t), TRANSIENT THERMAL RESISTANCE (NORMALIZED)  $Z_{\theta JC(t)} = R_{\theta JC(t)} \bullet r(t)$ 0.1 0.1 10 100 1000 1·10<sup>4</sup> t, TIME (ms)

Figure 3. On-State Characteristics

Figure 4. Transient Thermal Response



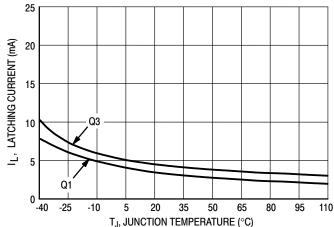


Figure 5. Typical Holding Current Versus **Junction Temperature** 

Figure 6. Typical Latching Current Versus **Junction Temperature** 

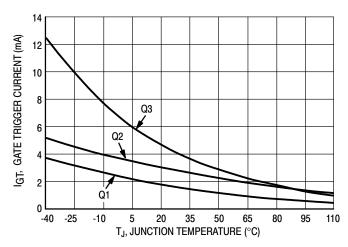


Figure 7. Typical Gate Trigger Current Versus
Junction Temperature

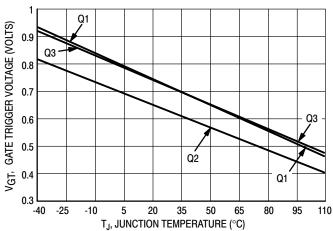


Figure 8. Typical Gate Trigger Voltage Versus
Junction Temperature

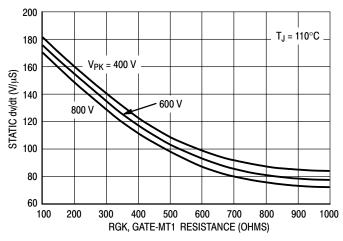


Figure 9. Typical Exponential Static dv/dt Versus
Gate-MT1 Resistance, MT2(+)

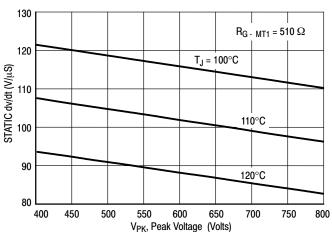


Figure 10. Typical Exponential Static dv/dt Versus Peak Voltage, MT2(+)

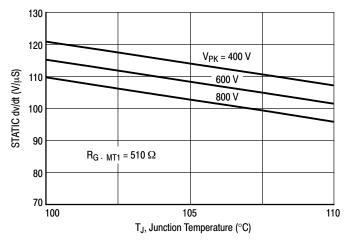


Figure 11. Typical Exponential Static dv/dt Versus
Junction Temperature, MT2(+)

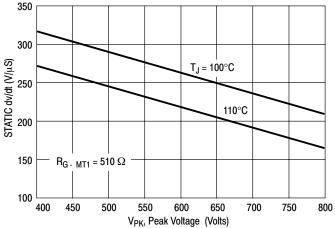


Figure 12. Typical Exponential Static dv/dt Versus Peak Voltage, MT2(-)

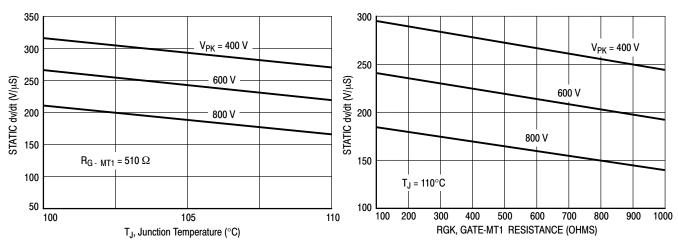
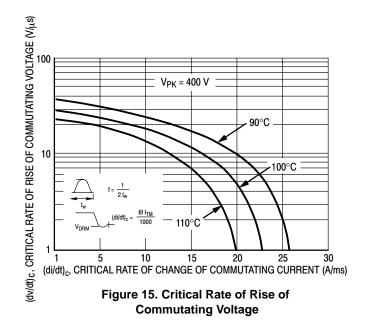
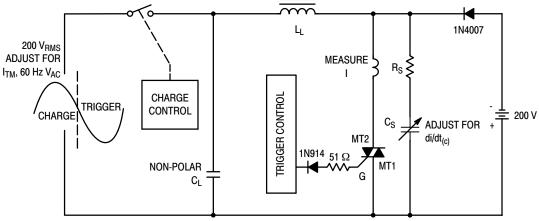


Figure 13. Typical Exponential Static dv/dt Versus Junction Temperature, MT2(-)

Figure 14. Typical Exponential Static dv/dt Versus Gate-MT1 Resistance, MT2(-)





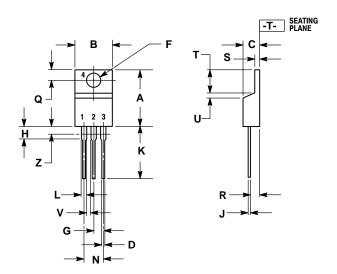
Note: Component values are for verification of rated (di/dt)<sub>c</sub>. See AN1048 for additional information.

Figure 16. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)c

### **PACKAGE DIMENSIONS**

#### **TO-220AB**

CASE 221A-09 **ISSUE AA** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

- STYLE 4:
  PIN 1. MAIN TERMINAL 1
  2. MAIN TERMINAL 2
  3. GATE
  4. MAIN TERMINAL 2

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